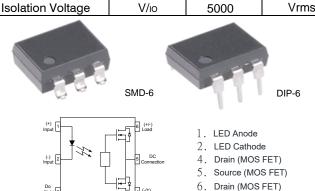
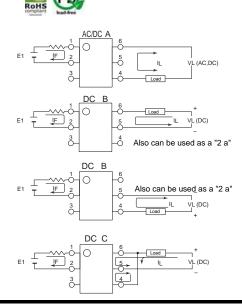
SUPSIC®

Parameter Units Symbol Rating V_{L} ٧ Load Voltage 600 Load Current ΙL 0.08 Α 35 On-Resistance R_{on} Ω I/O Isolation Voltage Vrms





SUPSiC PhotoRelays

- Long life (No limit on mechanical and electrical
- lifetime)Bounce-free switching
- Higher speed and high frequency switching
- Higher sensitivity (less power consumption)
- Immunity to EMI or RFI

- No have voltaic arc, bounce, and noise More
- resistant to vibration and impact AC or DC load
- switching
- Small package size

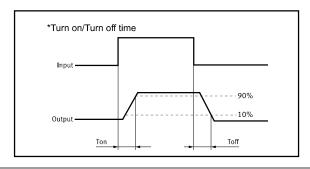
Applications

- Telecom/Datacom switching
- Multiplexers
- Meter reading systems
- Data acquisition
- Medical equipment
- Battery monitoring
- I/O Sub-Systems

- Robotics
- Aerospace
- Home/Safety security systems
- Process Control
- Energy Management
- Reed Relay EMR Replacement
- Programmable Controllers

TPYES

Category	Output Rating		Doolsono	Part No.	Doolsing Overtity	
	Load Voltage	Load Current	Package	Part No.	Packing Quantity	
AC/DC	600V	0.08A	DIP-6	GAQV216E	50pcs /tube	
			SMD-6	GAQV216EH	1000pcs /reel	





Absolute Maximum Ratings (Ta = 25°C)

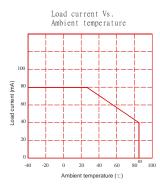
Item		Symbol	Va l ue	Units	Note	
Input	Continuous LED Current	I F	50	mA		
	Peak LED Current	I FP	1000	mA	f=100Hz, duty=1%	
	LED Reverse Voltage	VR	5	V		
	Input Power Dissipation	Pın	75	mW		
Output	Load Voltage	V∟	600	V(AC peak or DC)		
	Load Current	l.	0.08	Α		
	Peak Load Current	Peak	0.12	Α	100ms(1 pulse)	
	Output Power Dissipation	Pout	450	mW		
Total Power	Total Power Dissipation		500	mW		
I/O Isolation Voltage		V _{I/O}	5000	Vrms	RH=60%, 1min	
Operating Temperature		Торг	-40 to 85	°C		
Storage Temperature		T _{stg}	-40 to 100	°C		
Pin Soldering Temperature		Tsol	260	℃	10 sec max.	

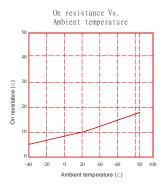
Electrical Characteristics (Ta = 25°C)

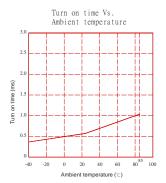
Item		Symbol	MIN.	TYP.	MAX.	Units	Conditions	
	LED Forward Voltage	VF		1.2	1.5	V	I⊧=10mA	
Input	Operation LED Current	Fon		0.5	5.0	mA		
	Recovery LED Current	Foff		0.35	0.5	mA		
	Recovery LED Voltage	V _{Foff}	0.7			V		
Output	On-Resistance	Ron		35	70	Ω	I⊧=5mA,I∟=Max Time to flow is within 1 sec.	
	Off-State Leakage Current	Leak			1	uA	V∟=Rating	
	Output Capacitance	Cout		100		pF	VL=0, f=1MHz	
Transmis	Turn-On Time	Ton		0.5	1.0	ms	I⊧=5mA, I∟=Max	
sion	Turn-Off Time	T _{off}		0.02	0.2	ms		
Coupled	I/O Isolation Resistance	Rio	10 ¹⁰			Ω	DC500V	
	I/O Capacitance	C _{I/O}		0.8	1.5	pF	f=1MHz	

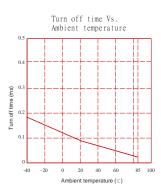
Please obey the following conditions to ensure proper device operation and resetting. Input LED current (Recommended value): IF \geq 5mA and \leq 30mA

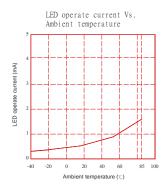
Engineering Data

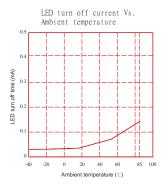


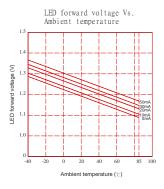


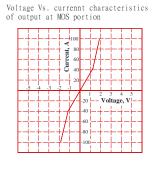


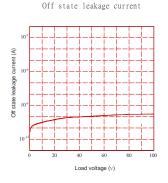


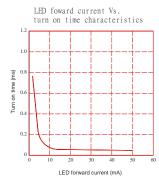


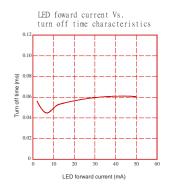


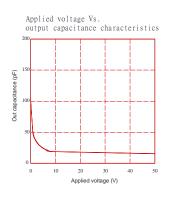










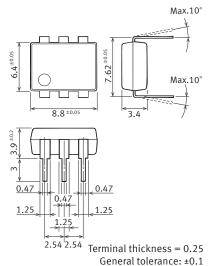


Dimensions and DIP-6 Package

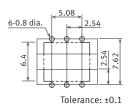
Unit: mm

Marking GAQV PART NO. YY=YEAR WW=WEEK XXXXXX

Through hole terminal type



PC board pattern (Bottom view)

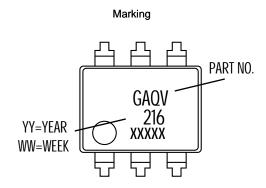


DIP Tape dimensions Unit: mm

Devices are packaged in a tube so that pin No. 1 is on the stopper B side. Observe correct orientation when mounting them on PC boards.



Dimensions and SMD-6 Package Unit: mm

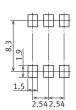


Surface mount terminal type Max.10° M

Terminal thickness = 0.25 General tolerance: ±0.1

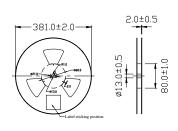
Recommended mounting pad

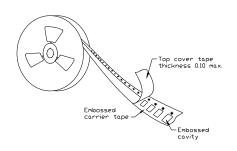
(Top view)

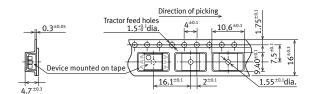


Tolerance: ±0.1

Tape dimensions (tape reel)



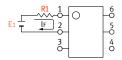


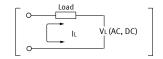




Using Methods

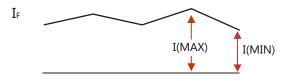
Examples of resistance value to control LED forward current (IF=5mA)





E1	R1 (Approx)
3.3V	300 Ω
5.0V	600 Ω
12V	1.9KΩ
24V	4.1K Ω

LED forward current must be more than 5mA , at I(MIN) ,and less than 30mA , at I(MAX).



Recommended Operating Conditions

Please obey the following conditions to ensure proper device operation and resetting. Input LED current (Recommended value):

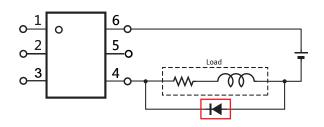
Characteristic	Symbol	Min	Тур.	Max	Unit
Forward current	IF	5.0	7.0	30	mA

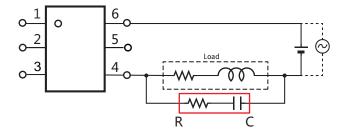
Protection Circuit

Output spike voltages:if an inductive load generates spike voltages which exceed heabsolute maximum rating, the spike voltage shall be limited.

Clamp diode is connected in parallel with the load. Absorb capacity with external diode.

CR Snubber is connected in parallel with the load. Absorb capacity with buffer capacity.





When adding diodes, buffer circuits (C-R), and other protections, they need to be installed near the MOS RELAY to be effective. Adding protection elements may result in a slow reset time, so adjust them according to the actual situation before use.

Note: When developing designs using this product, perform the expected performance of the equipment under the operating conditions recommended by the guidelines in this document. Continuous use under heavy loads (including, but not limited to, the application of high temperatures/current/voltage and significant changes in temperature, etc.) may result in deterioration of the reliability of this product.



Recommended Soldering Conditions

(a) Infrared reflow soldering:

■ Peak reflow soldering : 260°C or below (package surface temperature)

■ Time of peak reflow temperature : 10 sec
 ■ Time of temperature higher than 230°C : 30-60 sec
 ■ Time to preheat temperature from 180~190°C : 60-120 sec

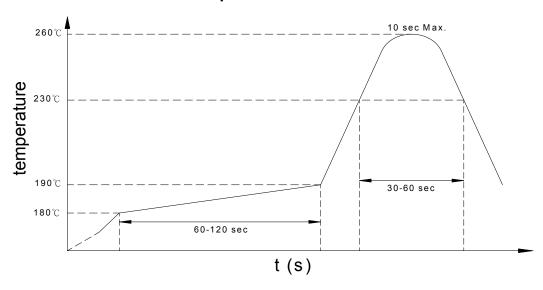
■ Time(s) of reflow: Two

■ Flux: Rosin flux containing small amount of chlorine (The

flux with a maximum chlorine content of 0.2 Wt% is

recommended.)

Recommended Temperature Profile of Infrared Reflow



(b) Wave soldering:

■ Temperature : 260°C or below (molten solder temperature)

■ Time : 10 seconds or less

■ Preheating conditions : 120°C or below (package surface temperature)

■ Time(s) of reflow : One

■ Flux: Rosin flux containing small amount of chlorine (The flux with a maximum

chlorine content of 0.2 Wt% is recommended.)

(c) Cautions:

■ Fluxes : Avoid removing the residual flux with freon-based and chlorine-based

cleaning solvent.

Avoid shorting between portion of frame and leads.